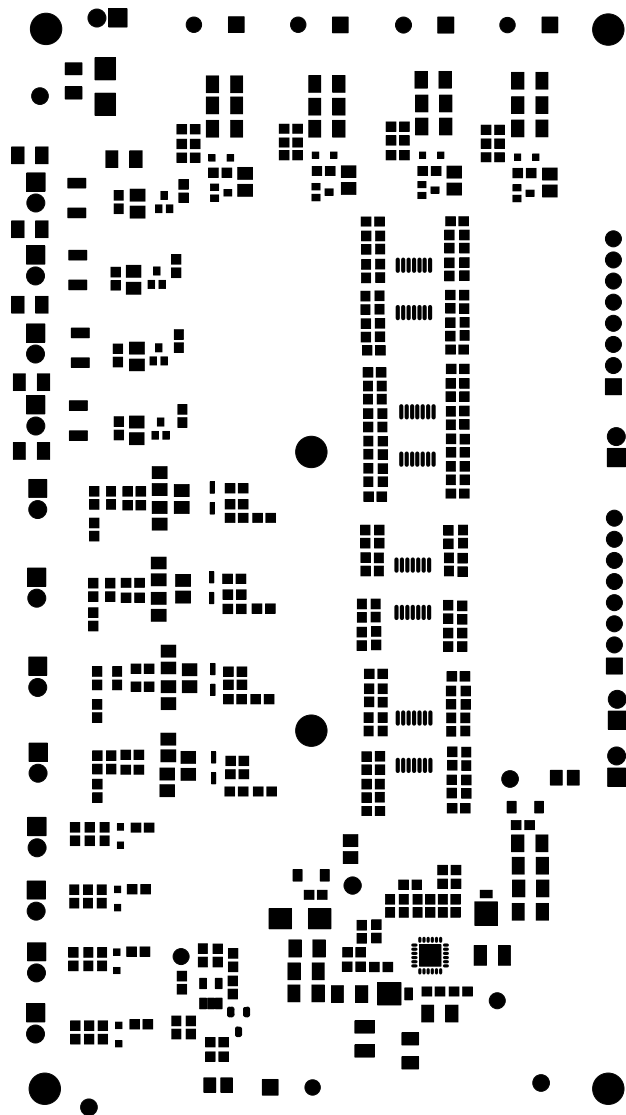
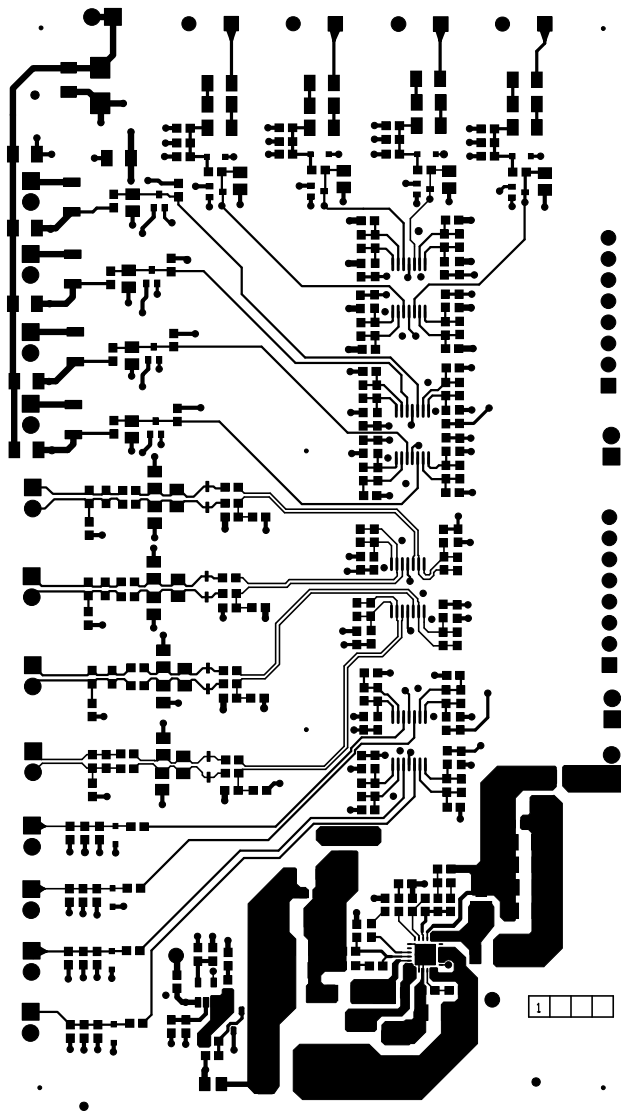


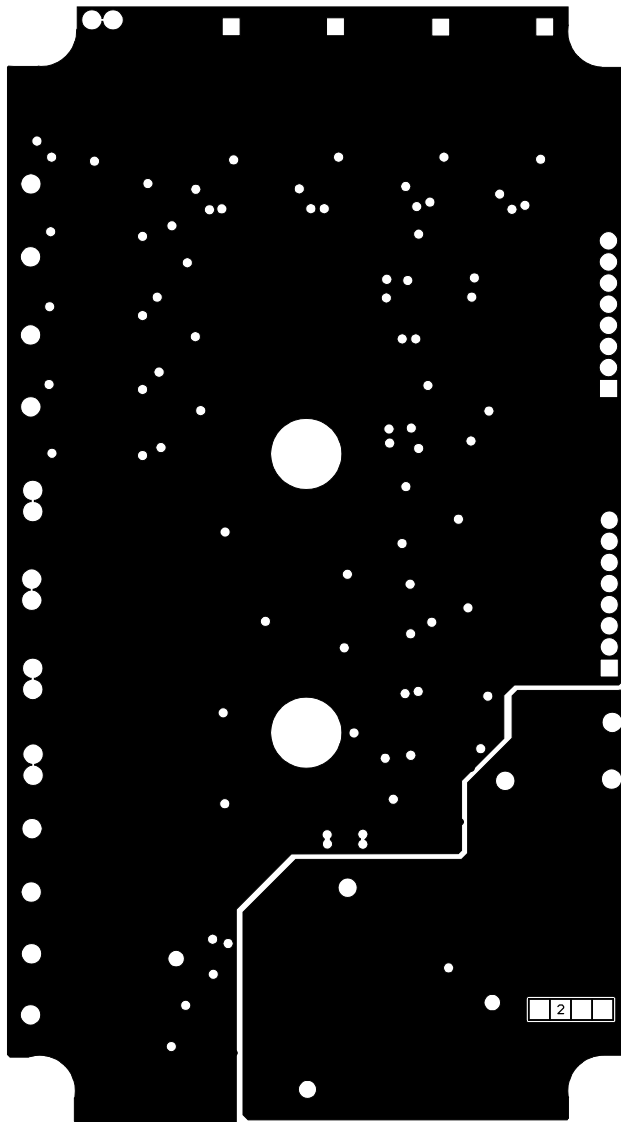
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TIDA-00493_E2.GTO	GENERATED : 5/22/2015 12:12:37 PM	TEXAS INSTRUMENTS	



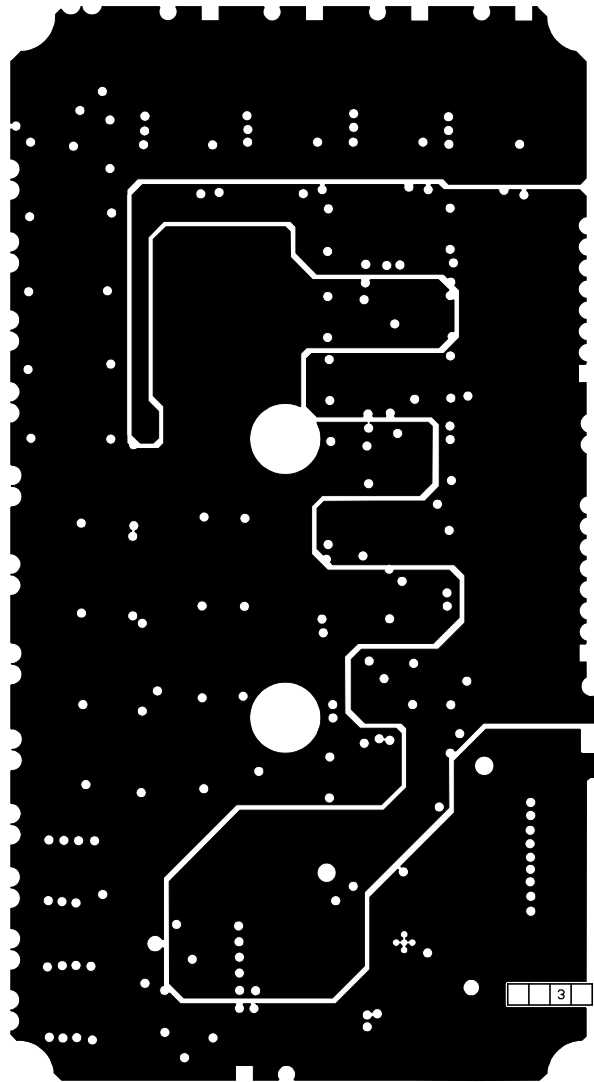
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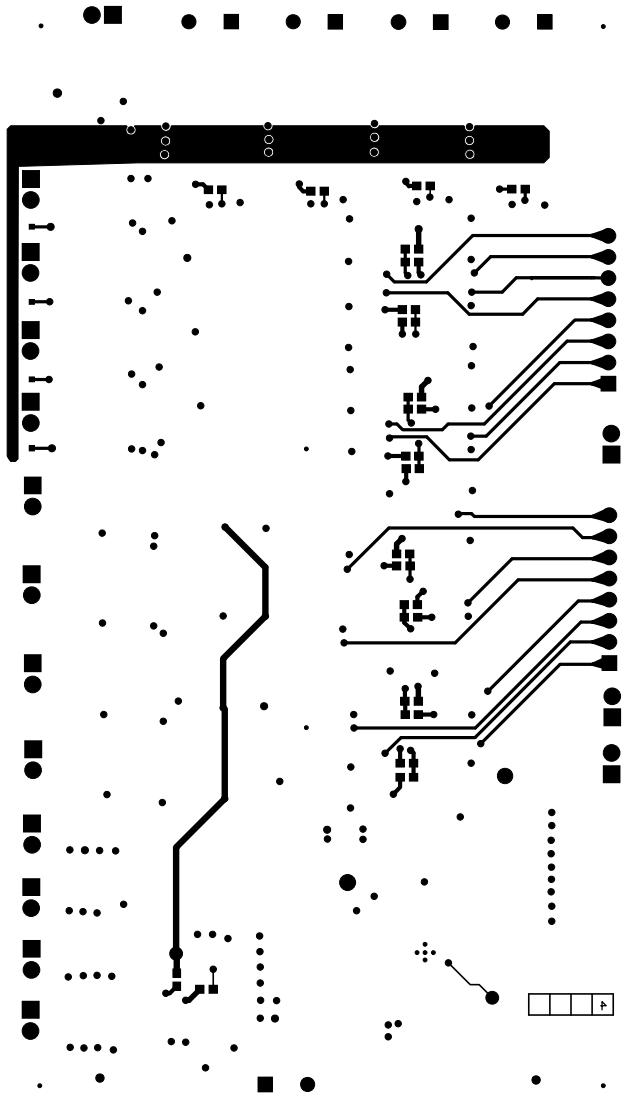
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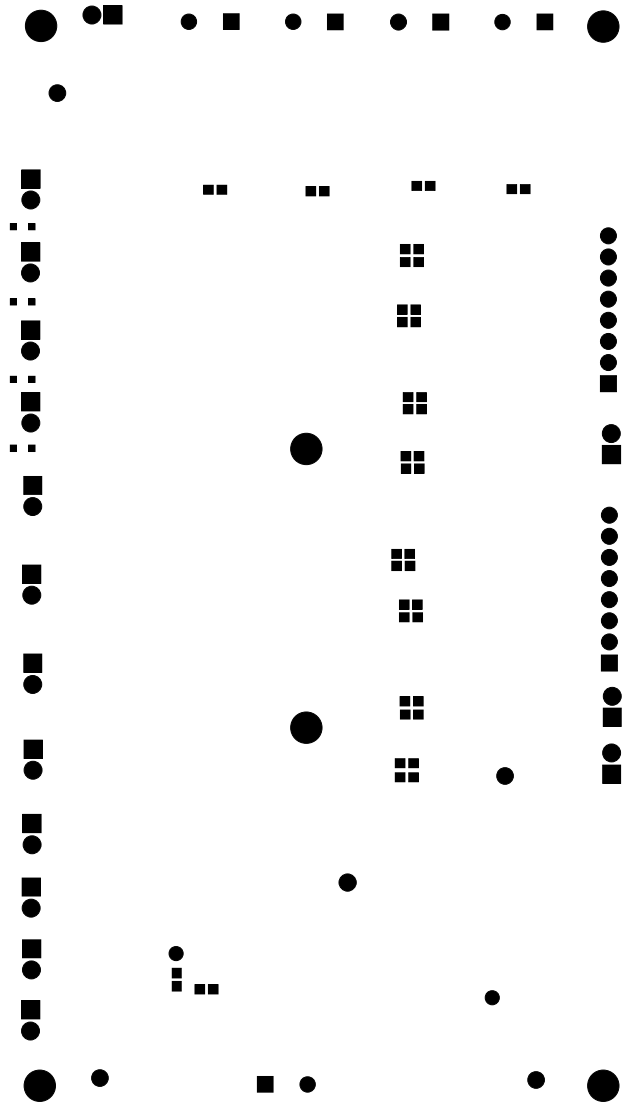
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LAYER NAME = MidLayer1			
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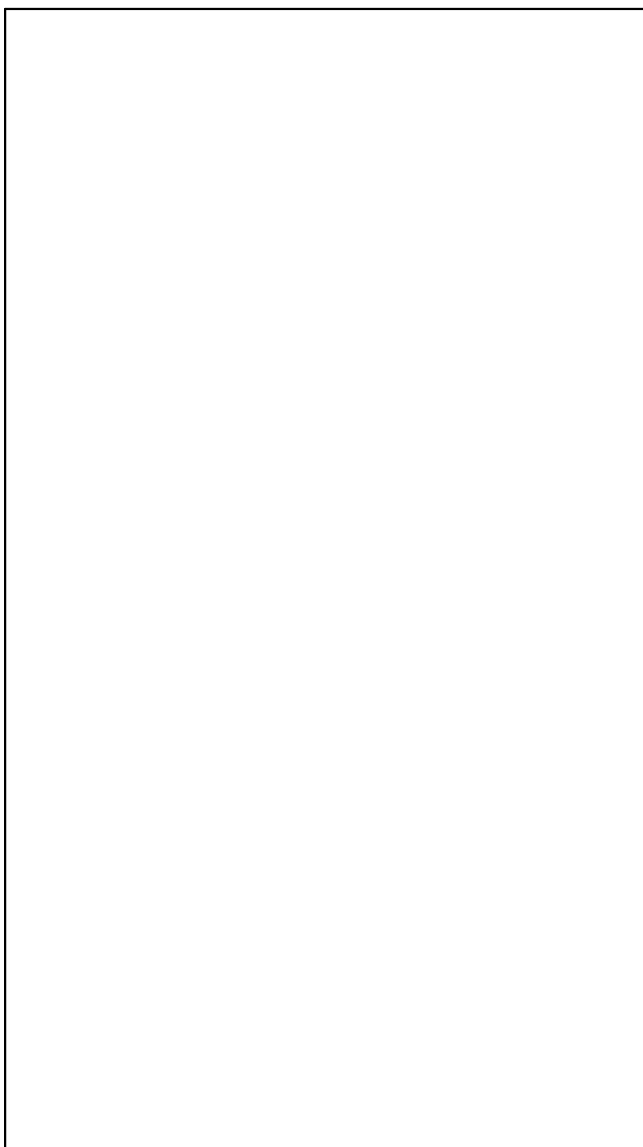
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LAYER NAME = MidLayer2			
TIDA-00493_E2.G2	GENERATED : 5/22/2015 12:12:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00493	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
TIDA-00493_E2.GBL	GENERATED : 5/22/2015	12:12:37 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00493	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
TIDA-00493_E2.GBS	GENERATED : 5/22/2015 12:12:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00493	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
TIDA-00493_E2.GMI	GENERATED	: 5/22/2015 12:19:23 PM	TEXAS INSTRUMENTS

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